



Material Content Data Sheet



Sales Product Name		TLS4120D0EP V33		Issued		4. July 2019			
MA#		MA003185362							
Package		PG-TSDSO-14-5		Weight*		64.44 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.632	4.08	4.08	40841	40841	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145		
		non noble metal	zinc	7440-66-6	0.037	0.06		579	
		non noble metal	iron	7439-89-6	0.746	1.16		11583	
wire	non noble metal	non noble metal	copper	7440-50-8	30.306	47.05	48.28	470316	482623
		non noble metal	copper	7440-50-8	0.261	0.40	0.40	4045	4045
		encapsulation	organic material	carbon black	1333-86-4	0.083	0.13		1295
encapsulation	plastics	epoxy resin	-	3.254	5.05		50499		
		inorganic material	silicondioxide	60676-86-0	24.475	37.98	43.16	379823	431617
leadfinish	non noble metal	tin	7440-31-5	1.644	2.55	2.55	25515	25515	
plating	noble metal	silver	7440-22-4	0.135	0.21	0.21	2094	2094	
glue	plastics	epoxy resin	-	0.214	0.33		3316		
		noble metal	silver	7440-22-4	0.641	0.99	1.32	9949	13265
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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